
**Surface chemical analysis — Depth
profiling — Methods for ion beam
alignment and the associated
measurement of current or current
density for depth profiling in AES and
XPS**

*Analyse chimique des surfaces — Profilage d'épaisseur — Méthodes
d'alignement du faisceau d'ions et la mesure associée de densité de
courant ou de courant pour le profilage d'épaisseur en AES et XPS*

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Contents

	Page
Foreword	iv
Introduction	v
1 Scope	1
2 Normative references	1
3 Terms, definitions, symbols and abbreviated terms	1
4 System requirements	2
4.1 General.....	2
4.2 Limitations.....	3
5 Ion beam alignment methods	3
5.1 General.....	3
5.2 Important issues to be considered prior to ion beam alignment.....	3
5.3 Alignment using circular-aperture Faraday cup.....	6
5.4 Alignment using elliptical-aperture Faraday cup.....	10
5.5 Alignment using images from ion-induced secondary electrons during ion beam rastering.....	10
5.6 Alignment in X-ray photoelectron microscope/photoelectron imaging system.....	12
5.7 Alignment by observing direct ion beam spot or crater image during and after ion sputtering.....	13
5.8 Alignment by observing phosphor sample.....	14
6 When to align and check ion beam alignment	14
Annex A (informative) Comparison of AES depth profiles with good/poor ion beam alignment	15
Annex B (informative) Alignment using cup with co-axial electrodes	17
Bibliography	19

ISO 16531:2020

<https://standards.iteh.ai/catalog/standards/iso/967a5ace-724d-47e4-bc8c-ef22d37f224f/iso-16531-2020>

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This document was prepared by Technical Committee ISO/TC 201, *Surface chemical analysis*, Subcommittee SC 4, *Depth profiling*.

This second edition cancels and replaces the first edition (ISO 16531:2013), which has been technically revised.

The main changes to the previous edition are as follows:

- **Table 1**, in reference to **5.4**: a comment has been added to mention the use of automated alignment routine.
- **5.3.2**, **5.3.3** and **5.5.4**: some descriptions in notes have been changed to body text.
- minor editorial changes have been introduced for clarity.

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